L	Hits	Search Text	DB	Time stamp
Number 101	10	"6119367" and (heat or heated or heater)	USPAT	2004/09/30
101	10	olisso, and (hear or heared or heater)	USPAT	11:54
_	57	"5569330"	USPAT;	2004/09/30
1			US-PGPUB;	07:42
			EPO; JPO;	' '
			DERWENT	
_	4	(("5569330") or ("5571337")).PN.	USPAT;	2004/09/30
			US-PGPUB;	07:45
	-	•	EPO; JPO; DERWENT	
l _	3	((WAFER or semiconductor or substrate)	USOCR	2004/09/30
		near20 (raised or raising or lifted or	OSOCK	10:00
		withdrawn)) same ("air knife" or "air		1 10.00
		wipe") and (washing or wash or clean or		•
		cleaning or rinse or rinsing or dry or		
		drying)		
-	20	1 ' '	USPAT;	2004/09/30
		near20 (raised or raising or lifted or	US-PGPUB;	07:51
		withdrawn)) same ("air knife" or "air	EPO; JPO;	
		wipe") and (washing or wash or clean or cleaning or rinse or rinsing or dry or	DERWENT	
		drying)		
_	37		USPAT;	2004/09/30
	1	wipe")	US-PGPUB;	07:54
			EPO; JPO;	
			DERWENT	
-	0	134/902.ccls. and ("air knife" or "air	USOCR	2004/09/30
ŀ		wipe")		07:55
-	2201	134/902.ccls.	USPAT;	2004/09/30
			US-PGPUB; EPO; JPO;	08:04
			DERWENT	
_	1481	134/902.ccls. and (tank or container or	USPAT;	2004/09/30
		vessel or receptacle or bath or vat or	US-PGPUB;	10:00
		tub)	EPO; JPO;	
			DERWENT	
-	4		USPAT;	2004/09/30
		or substrate) same ("air knife" or "air	US-PGPUB;	10:50
	1 .	wipe")	EPO; JPO;	
_	2	("6199564").PN.	DERWENT USPAT;	2004/09/30
	-	,	US-PGPUB;	10:28
			EPO; JPO;	
			DERWENT	
-	3	("3865298").PN.	USPAT;	2004/09/30
· ·			US-PGPUB;	10:29
			EPO; JPO;	'
_	2339	trafon on gomigandustan av	DERWENT	2004/00/20
-	2339	(wafer or semiconductor or substrate) same ("air knife" or "air wipe")	USPAT; US-PGPUB;	2004/09/30
		Same (all Mille of all wipe)	EPO; JPO;	10.31
	1		DERWENT	
-	1021	(wafer or semiconductor or substrate)	USPAT;	2004/09/30
		same ("air knife" or "air wipe") same	US-PGPUB;	10:51
		(drying or dry or dried)	EPO; JPO;	
	1000		DERWENT	0004/55/55
_	1023	(wafer or semiconductor or substrate)	USPAT;	2004/09/30
		same ("air knife" or "air wipe") same (drying or dry or dried)	US-PGPUB; EPO; JPO;	10:52
		tarying of ary or arrea/	DERWENT;	
			IBM TDB	
-	. 138	(wafer or semiconductor or substrate)	USOCR	2004/09/30
		same ("air knife" or "air wipe") same		10:54
		(drying or dry or dried)		
_	3	((wafer or semiconductor or substrate)	USPAT;	2004/09/30
		NEAR25 (pulled or lifted or raised or	US-PGPUB;	10:56
		withdrawn)) same ("air knife" or "air	EPO; JPO;	
		wipe") same (drying or dry or dried)	DERWENT;	
L	1		IBM TDB	1

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-	36	((wafer or semiconductor or substrate)	USPAT;	2004/09/30
		NEAR25 (pulled or lifted or raised or	US-PGPUB;	10:58
		withdrawn)) same ("air knife" or "air	EPO; JPO;	
		wipe")	DERWENT;	1
			IBM_TDB	
_	428	((wafer or semiconductor or substrate)	USPAT;	2004/09/30
		NEAR25 (pulled or lifted or raised or	US-PGPUB;	11:04
		withdrawn)) same (((air or gas) near15	EPO; JPO;	1
		(nozzle or jet)) or "air knife" or "air	DERWENT;	
		wipe")	IBM_TDB	
_	511	134/113.ccls.	USPAT	2004/09/30
		· ·		11:52

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